

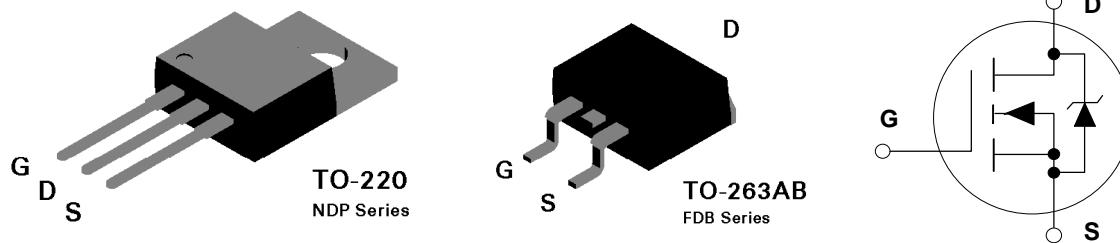
## NDP710A / NDP710AE / NDP710B / NDP710BE NDB710A / NDB710AE / NDB710B / NDB710BE N-Channel Enhancement Mode Field Effect Transistor

### General Description

These N-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

### Features

- 42 and 40A, 100V.  $R_{DS(ON)} = 0.038$  and  $0.042\Omega$ .
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design ( $3 \text{ million/in}^2$ ) for extremely low  $R_{DS(ON)}$ .
- TO-220 and TO-263 (D<sup>2</sup>PAK) package for both through hole and surface mount applications.



### Absolute Maximum Ratings

$T_c = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	NDP710A NDB710A	NDP710AE NDB710AE	NDP710B NDB710B	NDP710BE NDB710BE	Units
$V_{DSS}$	Drain-Source Voltage		100			V
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \leq 1 \text{ M}\Omega$ )		100			V
$V_{GSS}$	Gate-Source Voltage - Continuous		$\pm 20$			V
	- Nonrepetitive ( $t_p < 50 \mu\text{s}$ )		$\pm 40$			V
$I_D$	Drain Current - Continuous	42		40		A
	- Pulsed	168		160		A
$P_D$	Total Power Dissipation @ $T_c = 25^\circ\text{C}$		150			W
	Derate above $25^\circ\text{C}$		1			W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-65 to 175			$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		275			$^\circ\text{C}$

### Electrical Characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
<b>DRAIN-SOURCE AVALANCHE RATINGS (Note 1)</b>							
$E_{AS}$	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 25 \text{ V}$ , $I_D = 42 \text{ A}$	NDP710AE NDP710BE NDB710AE NDB710BE			700	mJ
$I_{AR}$	Maximum Drain-Source Avalanche Current					42	A
<b>OFF CHARACTERISTICS</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	ALL	100			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100 \text{ V}$ , $V_{GS} = 0 \text{ V}$ $T_J = 125^\circ\text{C}$	ALL			250	$\mu\text{A}$
$I_{GSSF}$	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}$ , $V_{DS} = 0 \text{ V}$	ALL			100	nA
$I_{GSSR}$	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}$ , $V_{DS} = 0 \text{ V}$	ALL			-100	nA
<b>ON CHARACTERISTICS (Note 2)</b>							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$ $T_J = 125^\circ\text{C}$	ALL	2	2.9	4	V
				1.4	2.2	3.6	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$ , $I_D = 21 \text{ A}$ $T_J = 125^\circ\text{C}$	NDP710A NDP710AE NDB710A NDB710AE		0.026	0.038	$\Omega$
					0.044	0.08	$\Omega$
		$V_{GS} = 10 \text{ V}$ , $I_D = 20 \text{ A}$ $T_J = 125^\circ\text{C}$	NDP710B NDP710BE NDB710B NDB710BE			0.042	$\Omega$
						0.09	$\Omega$
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10 \text{ V}$ , $V_{DS} = 10 \text{ V}$	NDP710A NDP710AE NDB710A NDB710AE	42			A
				NDP710B NDP710BE NDB710B NDB710BE	40		A
$g_{FS}$	Forward Transconductance	$V_{DS} = 10 \text{ V}$ , $I_D = 21 \text{ A}$	ALL	20	28		S
<b>DYNAMIC CHARACTERISTICS</b>							
$C_{iss}$	Input Capacitance	$V_{DS} = 25 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	ALL		2840	3600	pF
$C_{oss}$	Output Capacitance		ALL		550	700	pF
$C_{rss}$	Reverse Transfer Capacitance		ALL		175	200	pF

NDP710.SAM

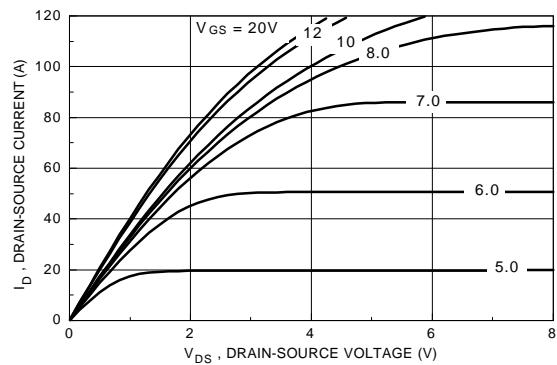
## Electrical Characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
<b>SWITCHING CHARACTERISTICS</b> (Note 2)							
$t_{D(ON)}$	Turn - On Delay Time	$V_{DD} = 50 \text{ V}, I_D = 42 \text{ A}, V_{GS} = 10 \text{ V}, R_{GEN} = 5 \Omega$	ALL		15	25	nS
$t_r$	Turn - On Rise Time		ALL		111	180	nS
$t_{D(OFF)}$	Turn - Off Delay Time		ALL		55	90	nS
$t_f$	Turn - Off Fall Time		ALL		81	130	nS
$Q_g$	Total Gate Charge	$V_{DS} = 80 \text{ V}, I_D = 42 \text{ A}, V_{GS} = 10 \text{ V}$	ALL		92	130	nC
$Q_{gs}$	Gate-Source Charge		ALL		15		nC
$Q_{gd}$	Gate-Drain Charge		ALL		44		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>							
$I_s$	Maximum Continuos Drain-Source Diode Forward Current	$V_{GS} = 0 \text{ V}, I_s = 21 \text{ A}$	NDP710A NDP710AE NDB710A NDB710AE			42	A
			NDP710B NDP710BE NDB710B NDB710BE			40	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	$T_J = 125^\circ\text{C}$	NDP710A NDP710AE NDB710A NDB710AE			168	A
			NDP710B NDP710BE NDB710B NDB710BE			160	A
$V_{SD}$ (Note 2)	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_s = 21 \text{ A}$	ALL		0.89	1.3	V
					0.69	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_s = 42 \text{ A}, dI_s/dt = 100 \text{ A}/\mu\text{s}$	ALL		128	180	ns
$I_{rr}$	Reverse Recovery Current		ALL		8.7	13	A
<b> THERMAL CHARACTERISTICS</b>							
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		ALL			1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		ALL			62.5	°C/W

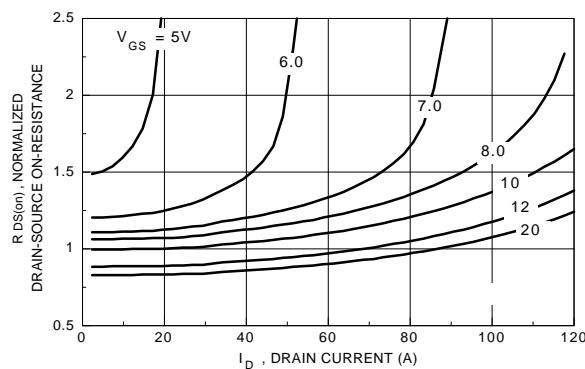
Notes:

1. NDP710A/710B and NDB710A/710B are not rated for operation in avalanche mode.
2. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

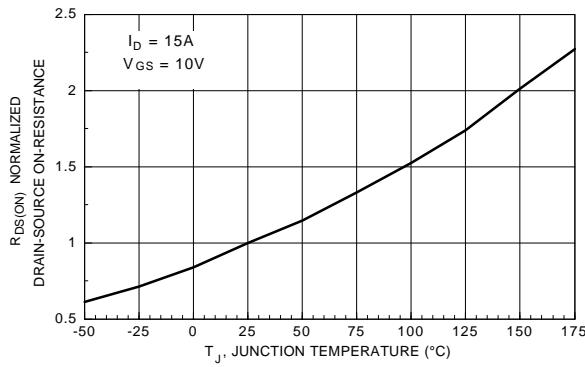
## Typical Electrical Characteristics



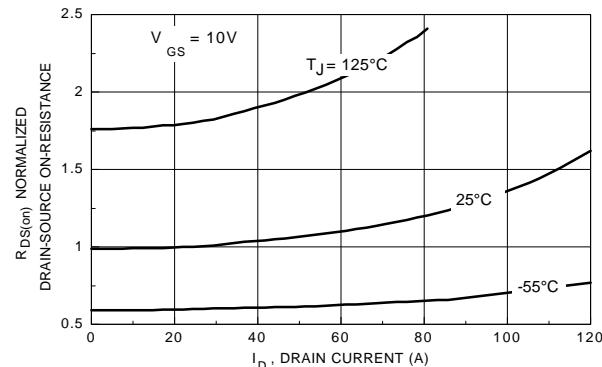
**Figure 1. On-Region Characteristics.**



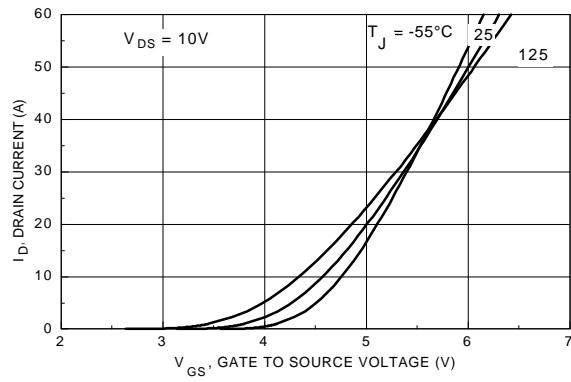
**Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.**



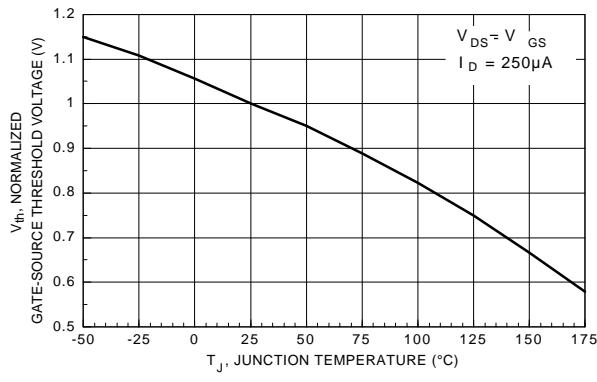
**Figure 3. On-Resistance Variation with Temperature.**



**Figure 4. On-Resistance Variation with Drain Current and Temperature.**

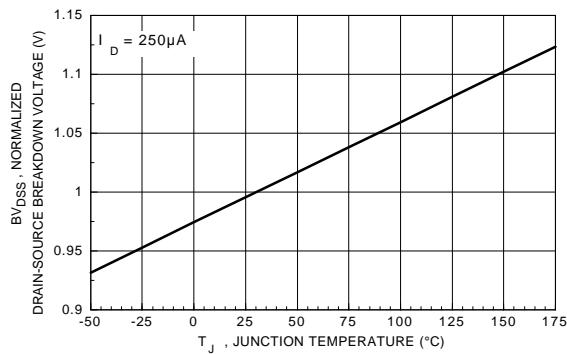


**Figure 5. Transfer Characteristics.**

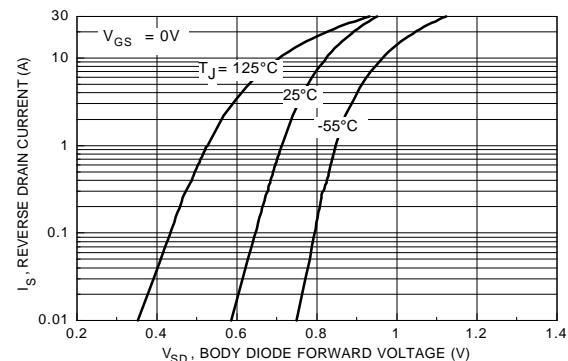


**Figure 6. Gate Threshold Variation with Temperature.**

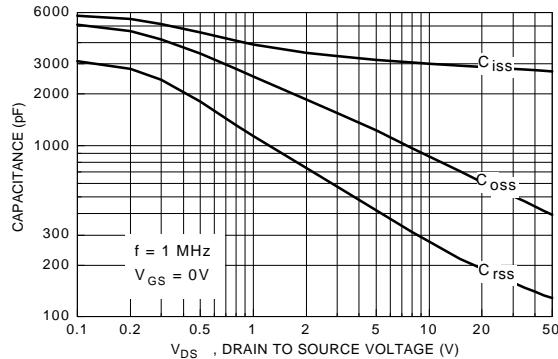
## Typical Electrical Characteristics (continued)



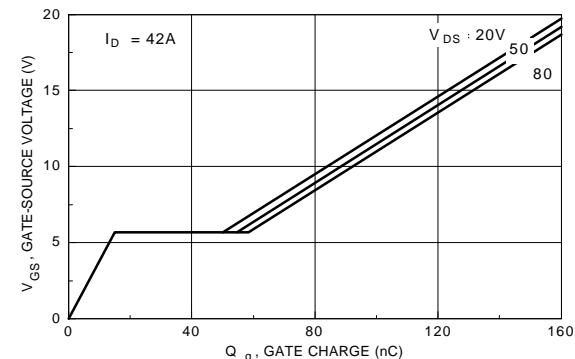
**Figure 7. Breakdown Voltage Variation with Temperature.**



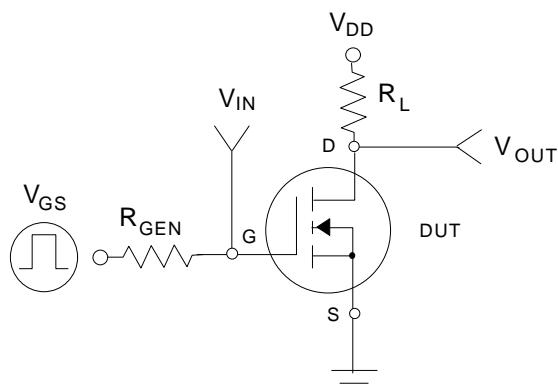
**Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.**



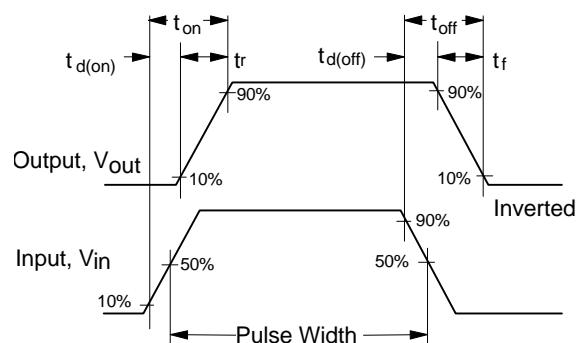
**Figure 9. Capacitance Characteristics.**



**Figure 10. Gate Charge Characteristics.**

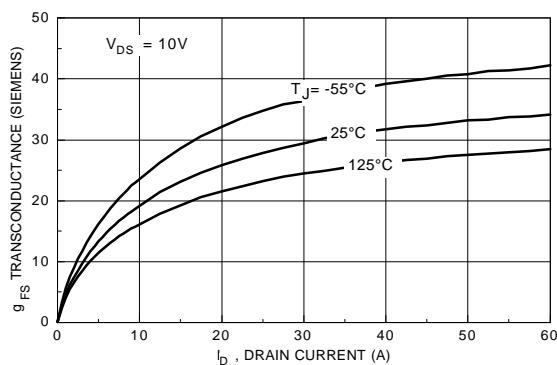


**Figure 36. Switching Test Circuit.**

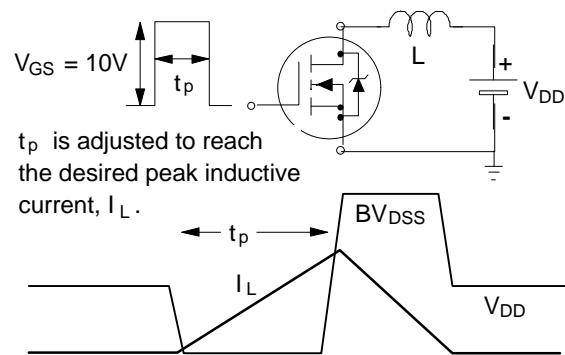


**Figure 12. Switching Waveforms.**

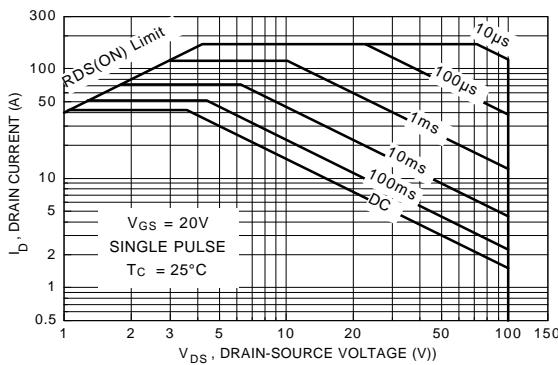
## Typical Electrical Characteristics (continued)



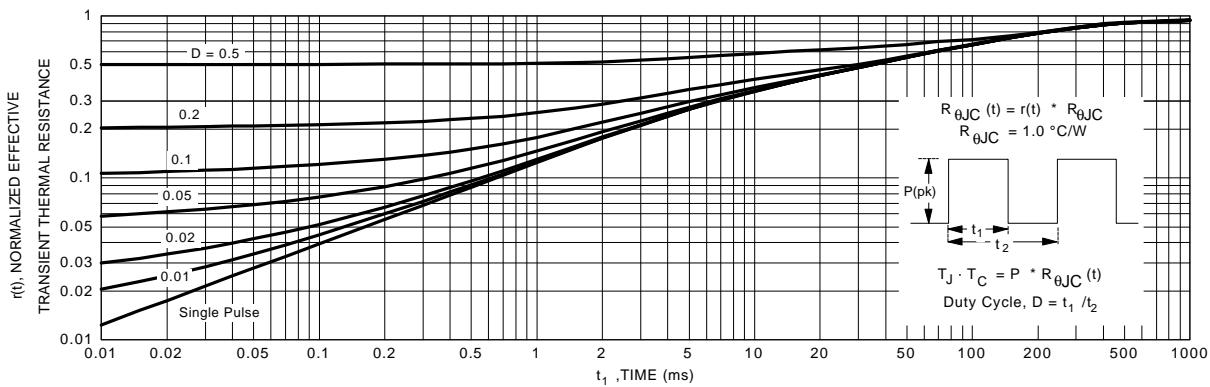
**Figure 13. Transconductance Variation with Drain Current and Temperature.**



**Figure 14. Unclamped Inductive Load Circuit and Waveforms.**



**Figure 15. Maximum Safe Operating Area.**



**Figure 16. Transient Thermal Response Curve.**